

Performance Gap Filler Pad

TP400-4-55 elevates the thermal performance bar, achieving 4 W/mK while maintaining a hardness of 55 (shore 00). The low hardness in comparison to thermal conductivity proves that TP400-4-55 will meet the demands of your challenging design requirements.



Features and Benefits

- 4.0 W/mK
- Low Silicone Oil Extraction
- Naturally tacky, easing application
- Low pressure versus deflection
- Excellent, high volume applications
- Elevated Temperature Resistance

Typical Applications

- Networking and Telecommunications
- IT: Notebooks, Tablets, Power Conversion
- Industrial: LEDs, Power Supplies and Conversion
- Automotive: Control Modules, Turbo Actuators
- Consumer Electronics: Gaming Systems, LCDs, and Graphic Cards

HOW TO ORDER

Patron THER TP400-4-55 XXX-YYY-ZZmm
XXX = width in mm
YYY = depth in mm
ZZ = thickness in mm

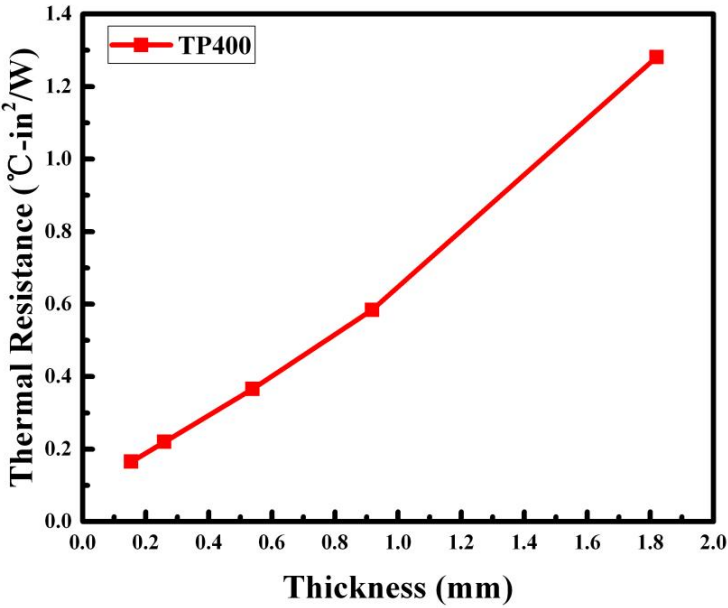
TYPICAL PROPERTIES

Attribute	Value	Test Method
	TP400-4-55	-
Composition	Ceramic Filler + Silicone	-
Color	Purple	Visual
Thickness (mm)	0.5 to 10.0	ASTM D374
Density (g/cc)	3.1	ASTM D792
Hardness (Shore OO)	55 (Thickness≤1.0 Shore OO 60)	ASTM D2240
Usage Temperature (°C)	- 60 to 200	-
Electrical		
Breakdown Voltage (kV/mm)	> 6.0	ASTM D149
Volume Resistivity (Ω.cm)	10^{13}	ASTM D257
Dielectric Constant	<7.5	ASTM D150
Flammability	V-0	UL 94
Thermal		
Thermal Conductivity (W/m-K)	4.0	ISO 22007-2

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Thickness vs. Thermal Resistance

Reference only



Pressure vs. Deflection

Reference only

